
EE141- Spring 2002

Introduction to Digital Integrated Circuits

Tu-Th 2:00-3:30pm
203 McLaughlin

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What is this class about?

- **Introduction to digital integrated circuits.**
 - » CMOS devices and manufacturing technology. CMOS inverters and gates. Propagation delay, noise margins, and power dissipation. Sequential circuits. Arithmetic, interconnect, and memories. Programmable logic arrays. Design methodologies.
- **What will you learn?**
 - » Understanding, designing, and optimizing digital circuits with respect to different quality metrics: cost, speed, power dissipation, and reliability

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Digital Integrated Circuits

- Introduction: Issues in digital design
- The CMOS inverter
- Combinational logic structures
- Sequential logic gates; timing
- Arithmetic building blocks
- Interconnect: R, L and C
- Memories and array structures
- Design methods

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Interludium: Administrativia

Instructors



Jan M. Rabaey
jan@eecs.berkeley.edu
Office hours: 231 Cory
Mo 4:00-5:30pm
Tu 1-2pm



Andrei Vladimirescu
andrei@bwrc.eecs.berkeley.edu
Office hours: 511 Cory
TBD

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The TA's



Josie Ammer

Discussion + lab
mjammer@bwrc.eecs.berkeley.edu
Office Hours: 353 Cory
We 10-11:30am



Tufan Karalar

Discussion + lab
tufan@bwrc.eecs.berkeley.edu
Office Hours: 297 Cory
Tu 11am-12:30pm



Jason Hu

Head Lab TA
hujas@bwrc.eecs.berkeley.edu
N.A.

The Web-Site

The sole source of information

<http://bwrc.eecs.berkeley.edu/Classes/ee141>

- Class and lecture notes
- Assignments and solutions
- Lab and project information
- Exams
- Many other goodies ...

Save a tree!

Class Admission

- Class is overenrolled
 - » Class room only seats 65 + 15
 - » But ... videotaped
 - » Also webcasted (<http://webcast.berkeley.edu>)
- Admission priorities
 - » Graduating seniors
 - » First-year grads
 - » Juniors, other grads
 - » Concurrent enrollment

Make sure your name is on the class roll!

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Discussions and Labs

- Discussion sessions
 - » Tu 4-5pm, 203 McLaughlin – Tufan
 - » We 9-10am, 293 Cory – Josie
 - » Pick any of the two (the are covering the same material)
- Labs (353 Cory)
 - » Mo 8-11am (Tufan)
 - » Mo 11-2pm -> Th 3:30-6:30pm (Jason)
 - » Tu 8-11am (Jason)
 - » W 11-2pm (Josie)
 - » Pick the one that fits you the best (pending availability) and **STICK TO IT!**

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The EE141 Week at a Glance

	8	9	10	11	12	1	2	3	4	5	6
M		Lab (Tufan) 353 Cory								OH (Jan) 231 Cory	
T		Lab (Jason) 353 Cory			OH (Tufan) 297 Cory	OH (Jan) 231 Cory	Lec (Jan) 203 McLaughlin		DISC* (Tufan) 203 McLaughlin		
W		DISC* (Josie) 293 Cory		OH (Josie) 353 Cory	Lab (Josie) 353 Cory						<- Problem Sets Due
R							Lec (Jan) 203 McLaughlin		Lab (Jason) 353 Cory		
F											

* Discussion sections will cover identical material

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Class Organization

- 10 Assignments
- A couple of design projects (1 term project)
- Labs: 6 software, 1 hardware
- 2 midterms, 1 final
 - » Midterm 1: Tu, February 6, 6:30-8:30pm
 - » Midterm 2: Th, April 11, 6:30-8:30pm
 - » Final: Fr. May 17, 12:30-3:30pm

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Grading Policy

- Homeworks: 10%
- Labs: 10%
- Projects: 20%
- Midterms: 30%
- Final: 30%

Class Material

- Textbook: "Digital Integrated Circuits – A Design Perspective", by J. Rabaey
- Class notes: Web page + Copy Central (New stuff!)
- Lab Reader:
 - Available on the web page!
 - Selected material will be made available from Copy Central
- Check web page for the availability of tools

Software

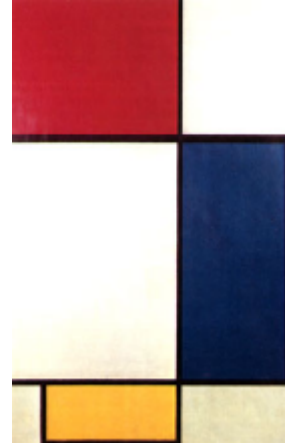
- MicroMagic
 - » Schematic editor: Sue
 - » Layout editor: Max
 - » Online documentation and tutorials
- HSPICE and IRSIM for simulation

Getting Started

- Assignment 1: Getting SPICE to work – see web-page
- NO discussion sessions or labs this week.
- First discussion sessions in Week 2
- First Software Lab in Week 2

Introduction

- Why is designing digital ICs different today than it was before?
- Will it change in future?



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The First Computer



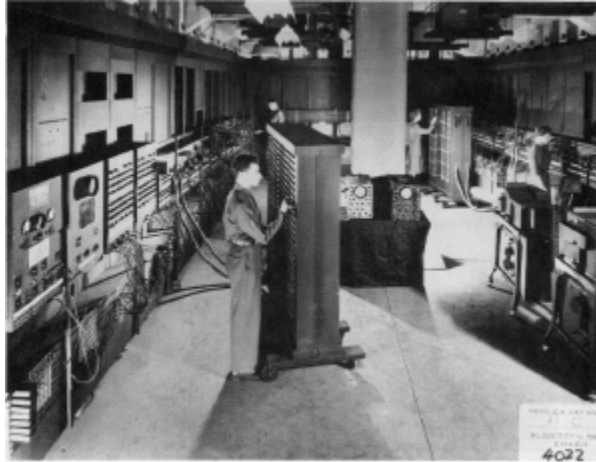
**The Babbage
Difference Engine
(1832)**

**25,000 parts
cost: £17,470**

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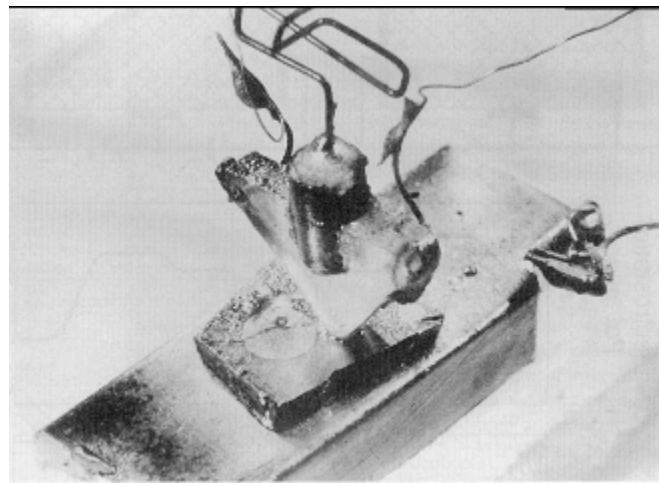
ENIAC - The first electronic computer (1946)



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The Transistor Revolution

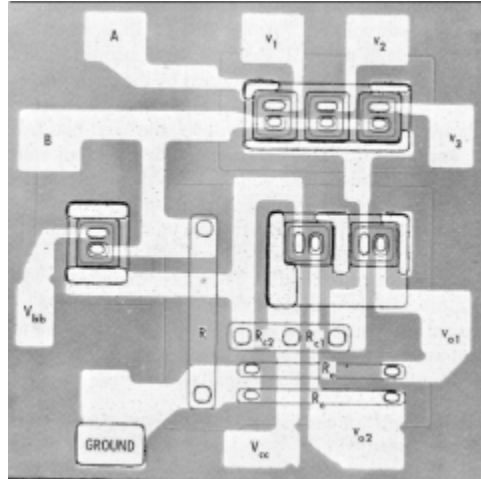


First transistor
Bell Labs, 1948

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The First Integrated Circuits



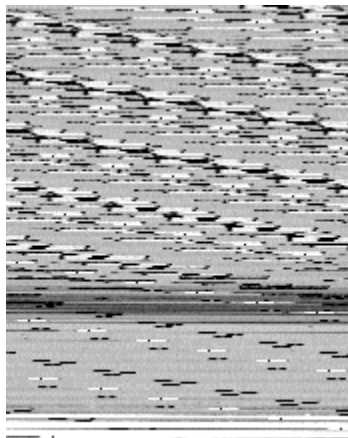
*Bipolar logic
1960's*

ECL 3-input Gate
Motorola 1966

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Intel 4004 Micro-Processor



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Moore's Law

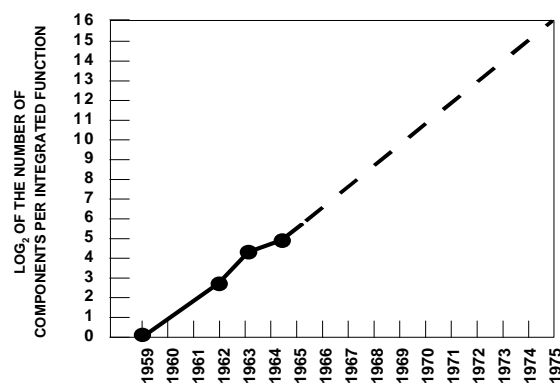
In 1965, Gordon Moore noted that the number of transistors on a chip doubled every 18 to 24 months.

He made a prediction that semiconductor technology will double its effectiveness every 18 months

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Moore's Law

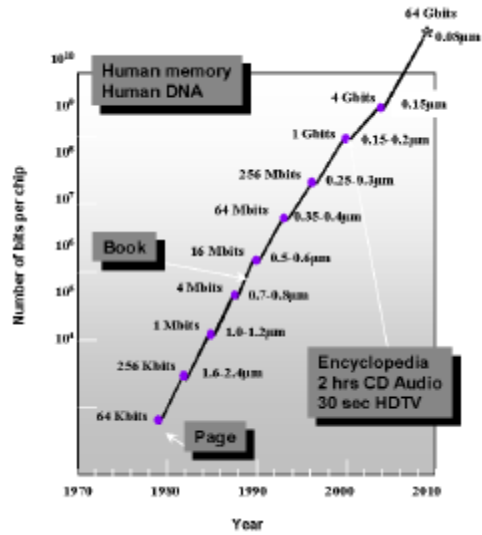


Electronics, April 19, 1965.

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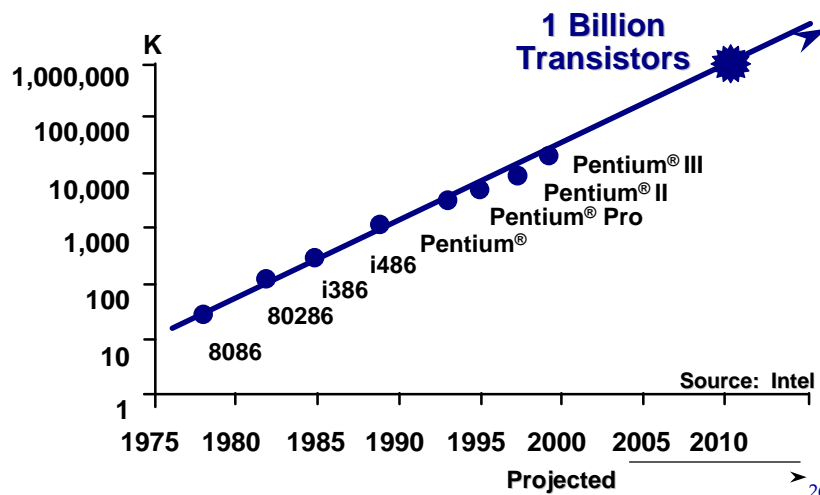
Evolution in Complexity



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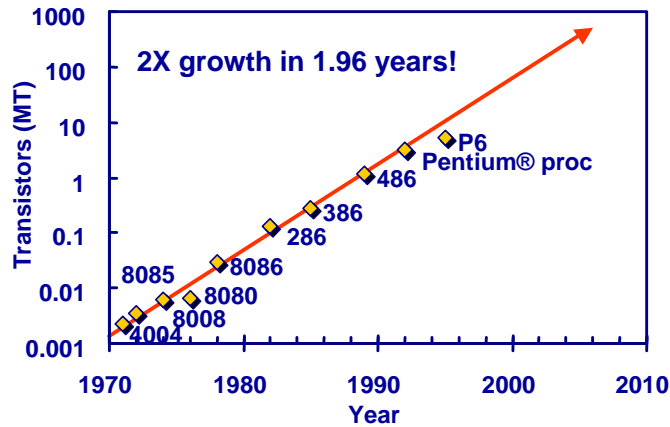
Transistor Counts



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Moore's law in Microprocessors



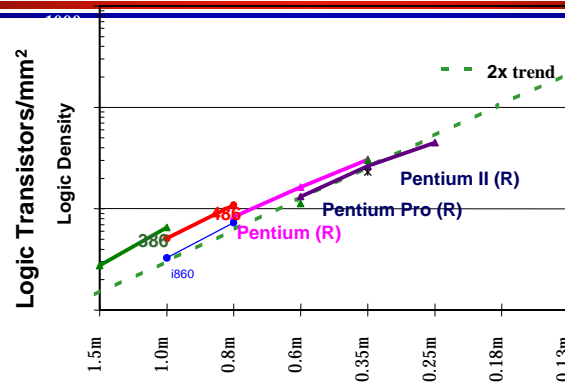
S. Borkar

Transistors on Lead Microprocessors double every 2 years

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Moore's Law - Logic Density



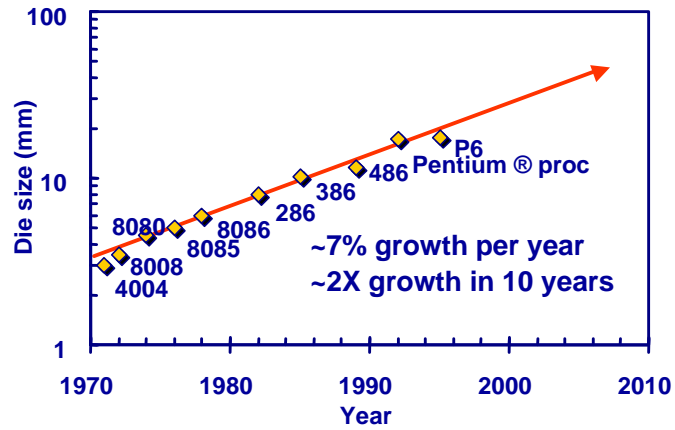
Source: Intel

↳ Shrinks and compactions meet density goals
 ✦ New micro-architectures drop density

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Die Size Growth



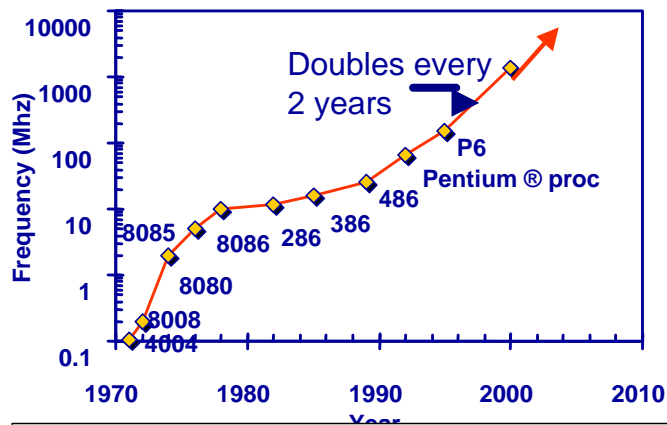
S. Borkar

Die size grows by 14% to satisfy Moore's Law

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Frequency



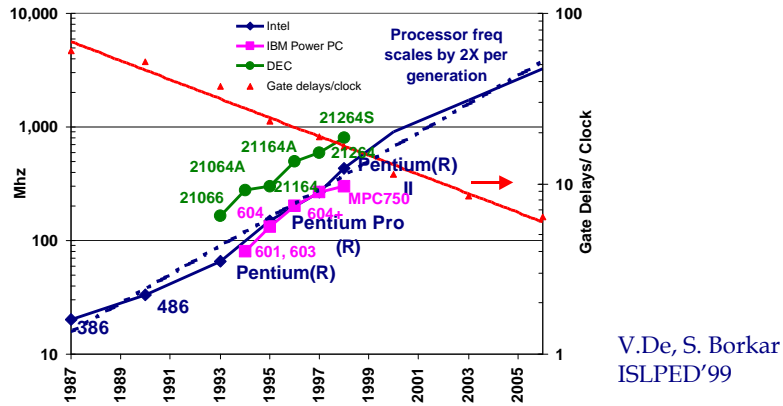
S. Borkar

Lead Microprocessors frequency doubles every 2 years

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Processor Frequency Trend

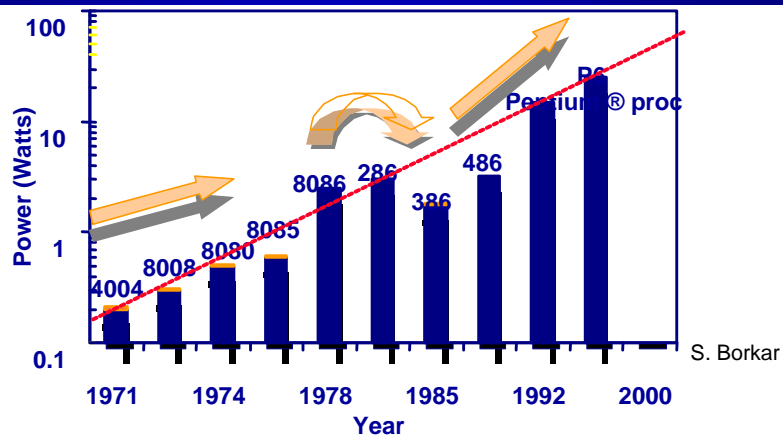


- Frequency doubles each generation
- ✂ Number of gates/clock reduce by 25%

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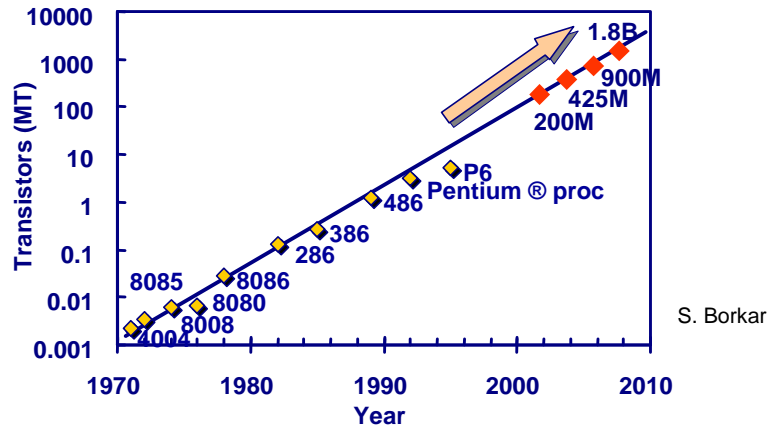
Power



Lead Microprocessors power continues to increase

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Obeying Moore's Law...

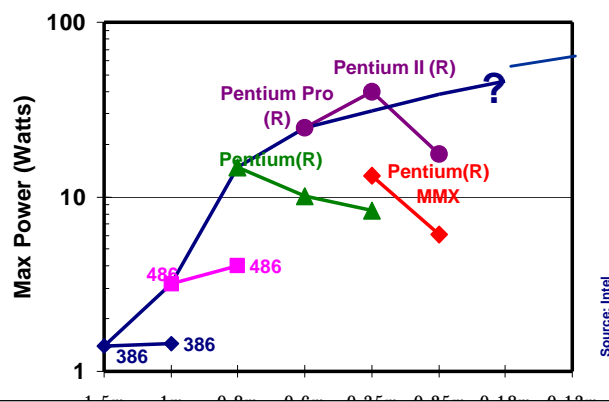


200M--1.8B transistors on the Lead Microprocessor

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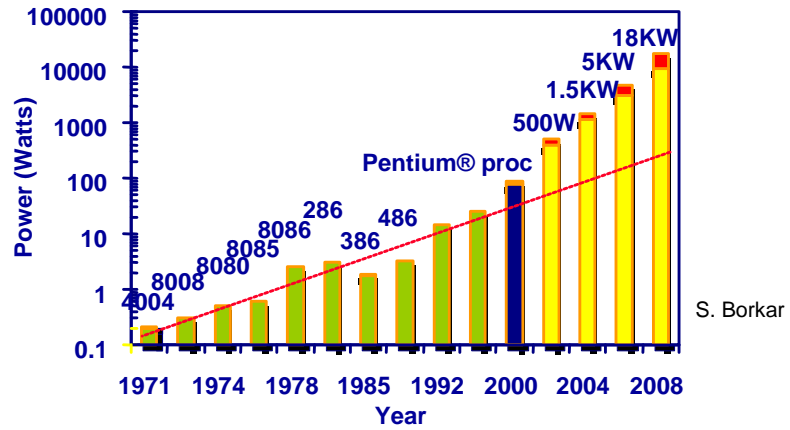
Processor Power



- Lead processor power increases every generation
- ✦ Compactions provide higher performance at lower power

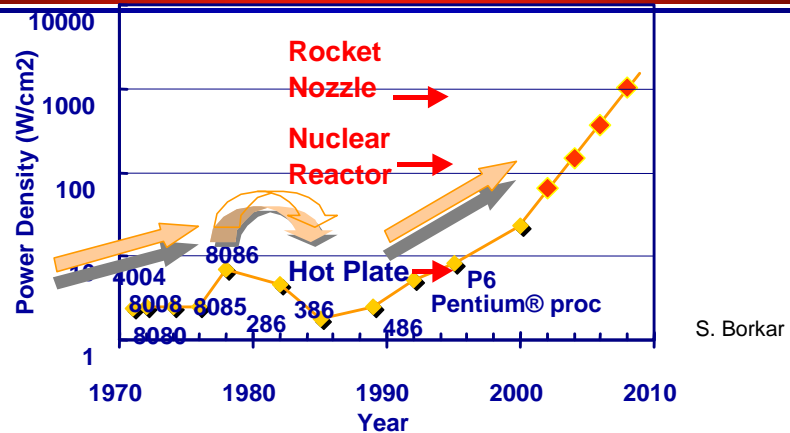
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Power will be a problem



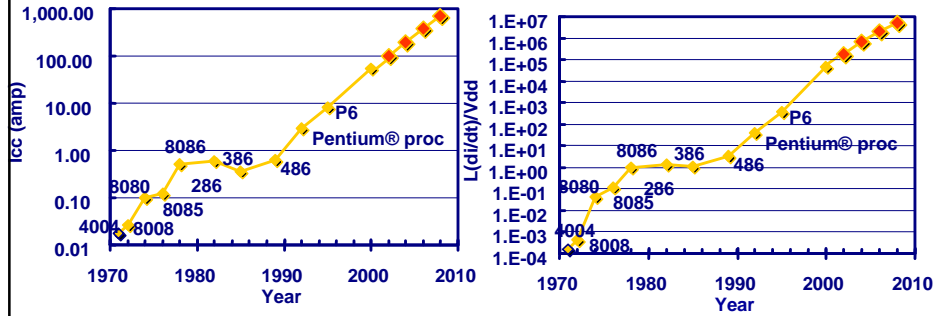
Power delivery and dissipation will be prohibitive

Power density will increase



Power density too high to keep junctions at low temp

Power delivery challenges



S. Borkar

High supply currents at low voltage:
Challenges: IR drop and $L(di/dt)$ noise

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Not Only Microprocessors

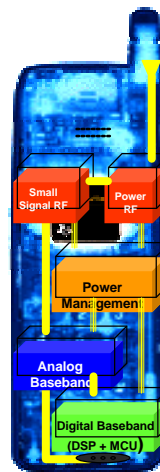
Cell Phone



Digital Cellular Market
(Phones Shipped)

	1996	1997	1998	1999	2000
Units	48M	86M	162M	260M	435M

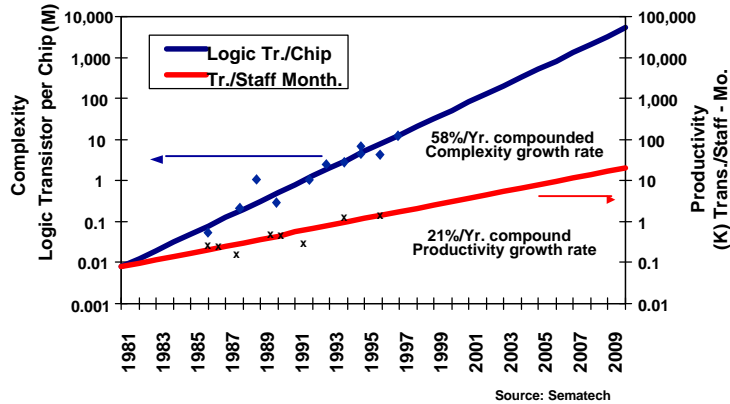
(data from Texas Instruments)



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Productivity Trends



Complexity outpaces design productivity

Challenges in Digital Design

μ DSM

“Microscopic Problems”

- Ultra-high speed design
- Interconnect
- Noise, Crosstalk
- Reliability, Manufacturability
- Power Dissipation
- Clock distribution.

Everything Looks a Little Different



?

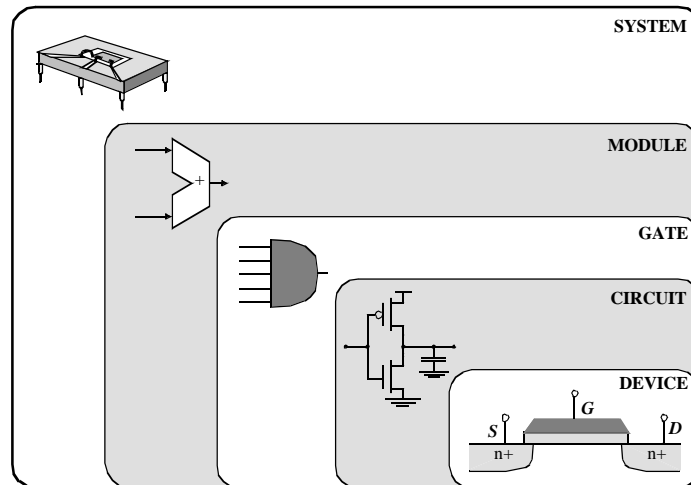
μ 1/DSM

“Macroscopic Issues”

- Time-to-Market
- Millions of Gates
- High-Level Abstractions
- Reuse & IP: Portability
- Predictability
- etc.

...and There's a Lot of Them!

Design Abstraction Levels



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Why Scaling?

- Technology shrinks by 0.7/generation
- With every generation can integrate 2x more functions per chip; chip cost does not increase significantly
- Cost of a function decreases by 2x
- How to design chips with more and more functions?
- Design engineering population does not double every two years...
- Need to understand different levels of abstraction

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Next Class

- Introduces basic metrics for design of integrated circuits – how to measure delay, power, etc.
- Brief intro to IC manufacturing and design